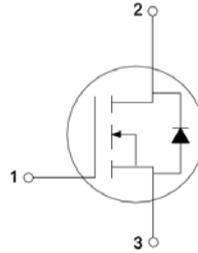


FEATURES

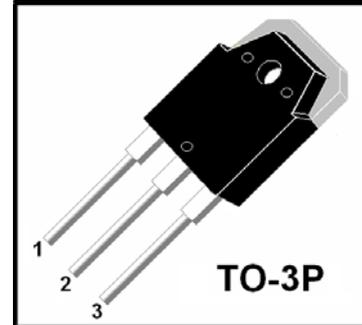
- Low drain-source ON resistance
- High forward transfer admittance
- Repetitive avalanche ratings
- Simple drive requirements
- Ease of paralleling

APPLICATIONS

- Switching power supplies
- Motor controls
- Inverters and choppers
- Audio amplifiers and energy pulse circuits



1.GATE
2.DRAIN
3.SOURCE



ABSOLUTE MAXIMUM RATINGS

T_C=25°C unless otherwise specified

Symbol	Parameter	Test Conditions	Values	Unit
V _{DSS}	Drain - Source Voltage	T _J =25°C	500	V
V _{GSS}	Gate - Source Voltage		±20	V
I _D	Continuous Drain Current	T _C =25°C	28	A
		T _C =100°C	20	A
I _{DM}	Pulsed Drain Current	Limited by T _{Jmax}	80	A
P _D	Maximum Power Dissipation		180	W
E _{AS}	Single Pulse Avalanche Energy		1000	mJ
I _{AR}	Avalanche Current		28	A
E _{AR}	Repetitive Avalanche Energy		25	mJ
T _J	Operating Junction		150	°C
T _{STG}	Storage Temperature Range		-55~150	°C
Weight			12	g

THERMAL CHARACTERISTICS

T_C=25°C unless otherwise specified

Symbol	Parameter	Test Conditions	Values	Unit
R _{th(ch-c)}	Thermal resistance,channel to case		0.7	°C/W
R _{th(ch-a)}	Thermal resistance,channel to ambient		40	°C/W

MM20N050P

ELECTRICAL CHARACTERISTICS

$T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	500			V	
$R_{DS(ON)}$	Drain-Source ON Resistance	$V_{GS}=10V, I_D=10A$		0.19		Ω	
		$V_{GS}=10V, I_D=20A$		0.20		Ω	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2.3	2.9	3.5	V	
I_{GSS}	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-200		200	nA	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=500V, V_{GS}=0V$			200	μA	
Q_g	Total Gate Charge	$V_{DD}=400V, I_D=20A, V_{GS}=10V$		136		nC	
Q_{gs}	Gate-Source Charge			37		nC	
Q_{gd}	Gate-Drain Charge			40		nC	
g_{fs}	Forward Transconductance	$V_{DS}=50V, I_D=10A$		18		S	
C_{iss}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$		4900		pF	
C_{oss}	Output Capacitance			990		pF	
C_{rss}	Reverse Transfer Capacitance			330		pF	
$t_{d(on)}$	Turn - on Delay Time	$V_{DD}=300V, I_D=20A,$ $R_G=5.1\Omega,$ $V_{GS}=10V,$ $R_L=15\Omega$	$T_J=25^\circ\text{C}$	35		ns	
			$T_J=125^\circ\text{C}$	40		ns	
t_r	Rise Time		$T_J=25^\circ\text{C}$	28		ns	
			$T_J=125^\circ\text{C}$	33		ns	
$t_{d(off)}$	Turn - off Delay Time		$T_J=25^\circ\text{C}$	120		ns	
			$T_J=125^\circ\text{C}$	125		ns	
t_f	Fall Time		$T_J=25^\circ\text{C}$		30		ns
			$T_J=125^\circ\text{C}$		35		ns

Source-Drain RATINGS AND CHARACTERISTICS

$T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD}	Continuous Source-Drain Current				20	A
I_{SDM}	Pulse Source-Drain Current				80	A
V_{SD}	Source-Drain Voltage	$I_{SD}=20A, V_{GS}=0V, T_J=25^\circ\text{C}$		0.85	1.6	V
t_{rr}	Reverse Recovery Time	$I_{SD}=20A, di_{SD}/dt=-100A/\mu s$ $T_J=25^\circ\text{C}$		495		ns
I_{RRM}	Max. Reverse Recovery Current			20		A
Q_{RRM}	Max. Reverse Recovery Charge			5.3		μC

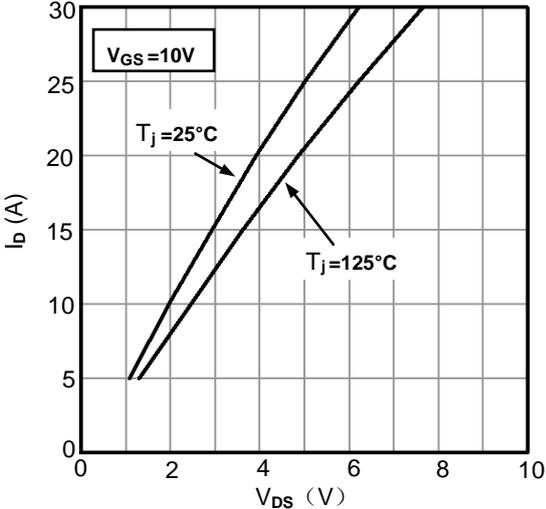


Figure1. Typical Output Characteristics

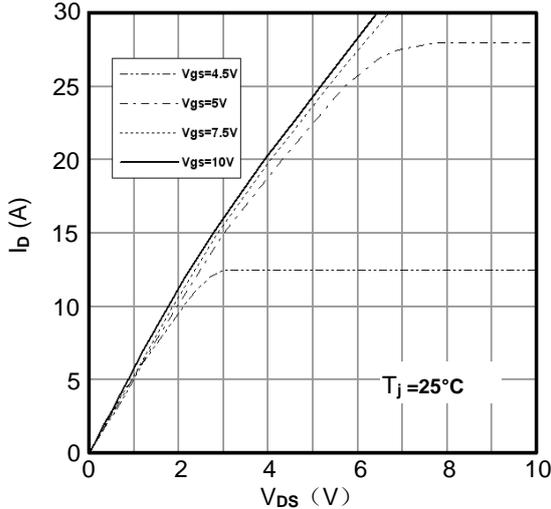


Figure2. Typical Output Characteristics

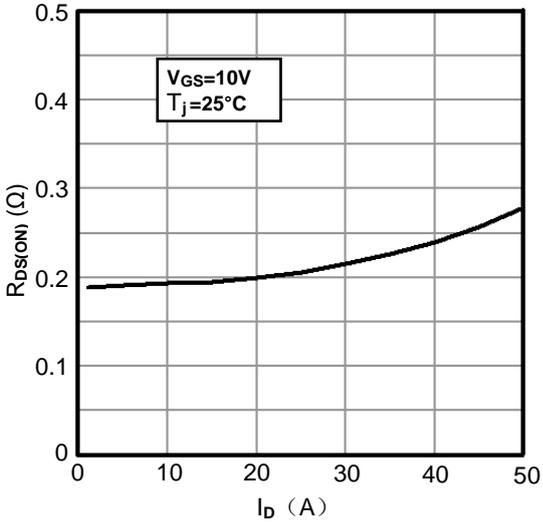


Figure3. Drain-Source ON Resistance vs. I_D

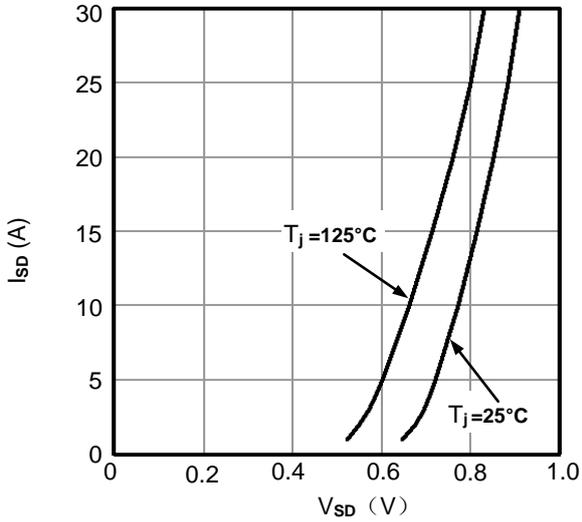


Figure4. Source-Drain Voltage

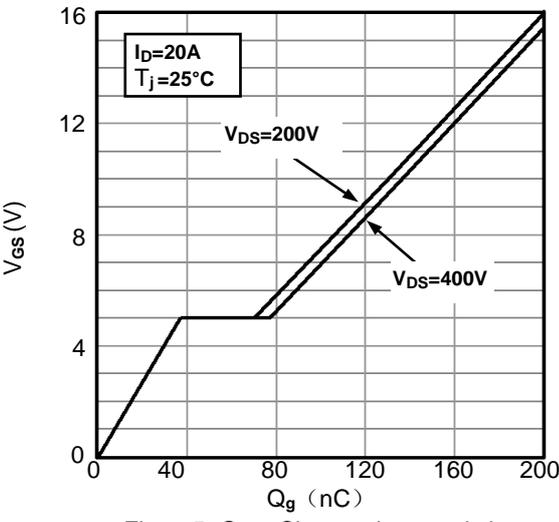


Figure5. Gate Charge characteristics

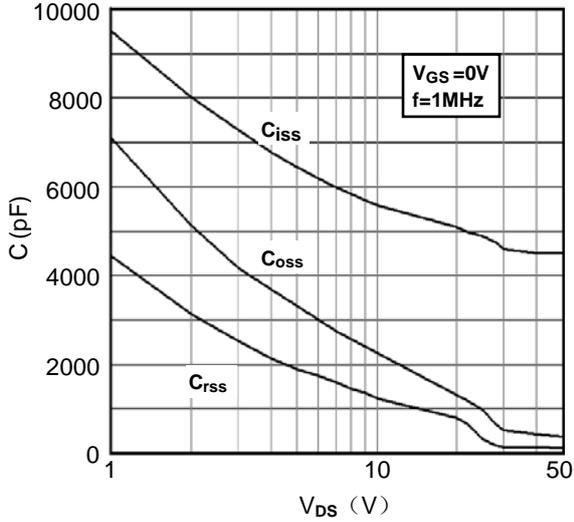


Figure6. Typical Capacitances vs. V_DS

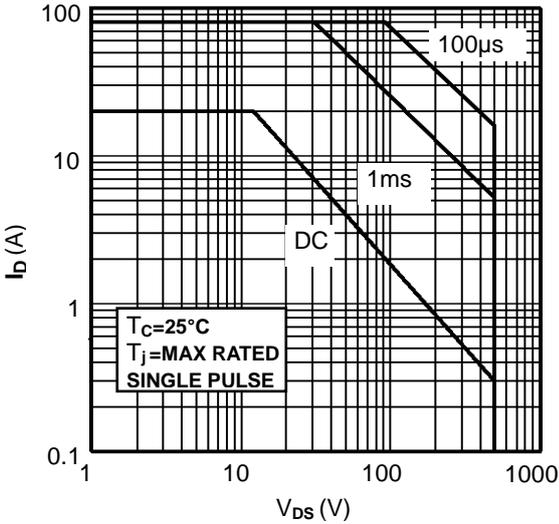


Figure 7. Forward Bias Safe Operating Area

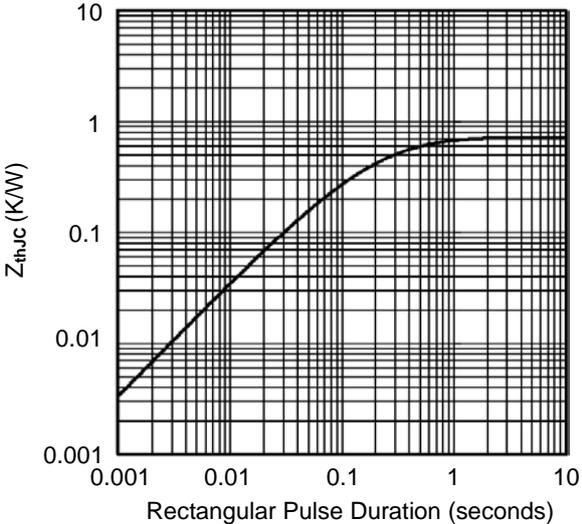


Figure 8. Transient Thermal Impedance

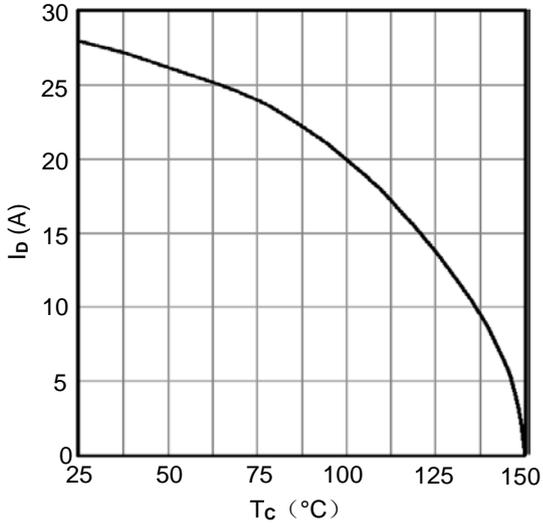


Figure 9. Maximum Continuous Drain Current vs. Case Temperature

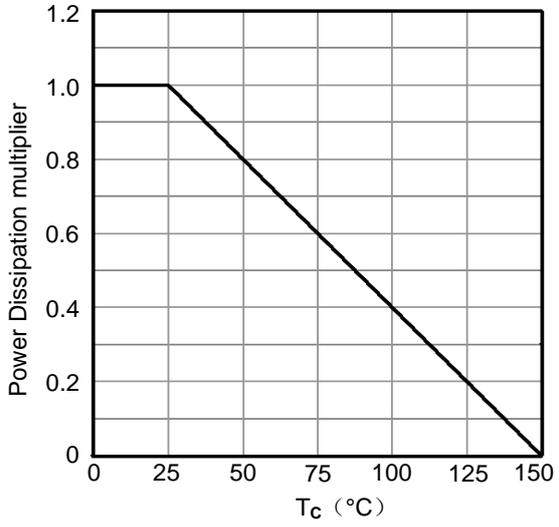


Figure 10. Normalized Power Dissipation vs. Case Temperature

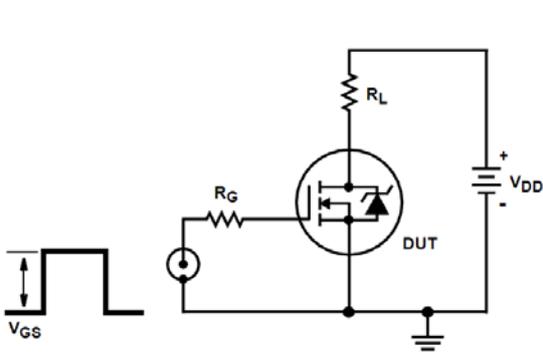


Figure 11. Switching Time Test Circuit

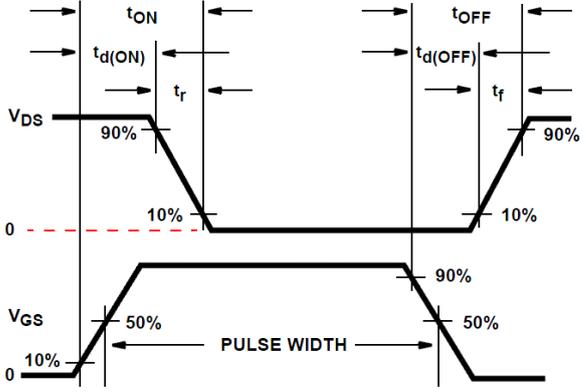


Figure 12. Resistive Switching Waveforms

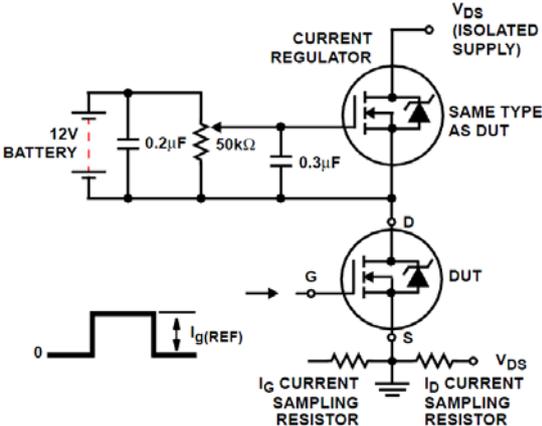


Figure13. Gate Charge Test Circuit

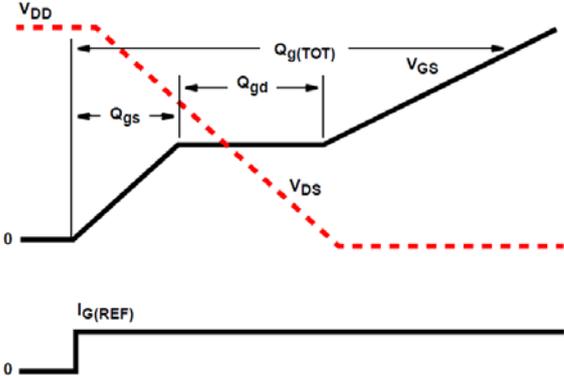
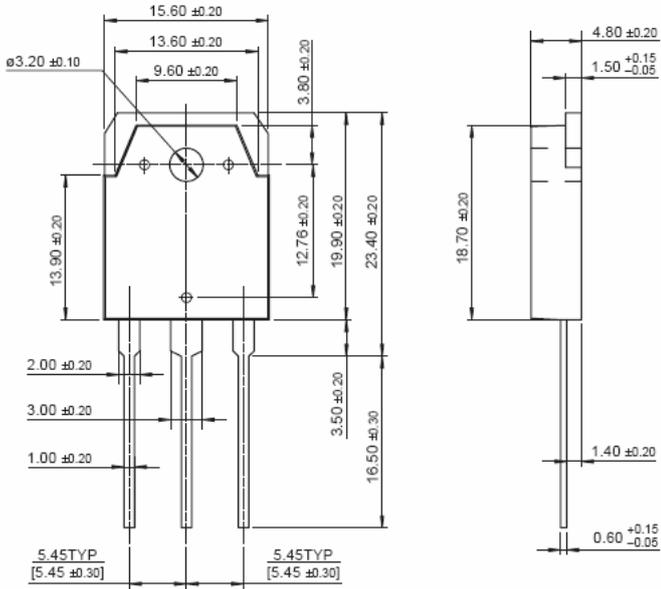


Figure14. Gate Charge Waveforms



Dimensions (mm)
Figure15. Package Outline